

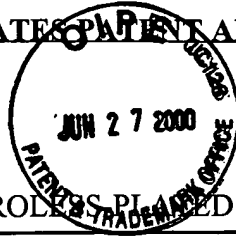
S/N 09/483,881

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.
Serial No.: 09/483,881
Filed: January 18, 2000
Title: SELECTIVE ELECTROLESS PLATED COPPER METALLIZATION

Examiner: Unknown
Group Art Unit: Unknown
Docket: 303.672US1



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mohit

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants further request that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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Date 6/23/2000 By Edward J. Brooks, III
Edward J. Brooks, III
Reg. No. 40,925

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner of Patents, Washington, D.C. 20231 on June 23, 2000.

Mina Uphus
Name

Mina Uphus
Signature

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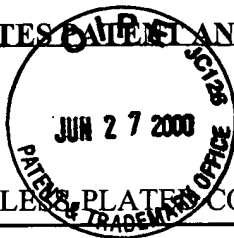
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COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)

Commissioner for Patents
Washington, D.C. 20231

Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

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Serial No.	Filing Date	Attorney Docket	Title
09/484,002	01/18/2000	00303.673US1	PROCESS FOR PROVIDING SEED LAYERS FOR USING ALUMINUM, COPPER, GOLD AND SILVER METALLURGY
09/484,303	01/18/2000	00303.648US1	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/483,869	01/18/2000	00303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/488,098	01/18/2000	00303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicant's Representatives,

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Date

6/23/2000

By

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